EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S11	481	(382/144).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 07:59
S12	759	(382/145).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 07:59
S13	216	(356/237.3).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 07:59
S14	423	(356/237.4).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 07:59
S15	649	(356/237.5).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 07:59
S16	1436	(716/19).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 08:01
S17	1039	(716/21).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 08:01
S18	1789	(700/121).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 08:01
S19	385	(700/109).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 08:00
S20	515	(700/110).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/03/14 08:00
S21	1128	S11 S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 08:01
S22	1076	S13 S14 S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 08:01
S23	783	S19 S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 09:10
S24	6025	S16 S17 S18 S21 S22 S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 09:19

EAST Search History

S25	0	test pattern (substrate article semiconductor wafer die) (current present) (condition state) reference (satisf$6 enough suffice sufficient$3 complet$4 good qualif$4 fulfill$3 pbtain$3 solv$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/03/14 09:26
S26	1569	S24 and (test and reference and pattern)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 09:20
S27	994	S24 and ((test and reference and pattern) and (current or present or preva$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 09:21
S28	484	S24 and ((test and reference and pattern) and ((current or present or preva$6) same (state or condition or status standing position shape situation circumstance)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 09:36
S29	0	test pattern (substrate article semiconductor wafer die) (current present status standing position shape situation circumstance) (condition state) (reference or example sample guide gold$3 (error near3 free)) (satisf$6 enough suffice sufficient$3 complet$4 good qualif$4 fulfill$3 pbtain$3 solv$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/03/14 09:36
S30	0	test pattern (substrate article semiconductor wafer die) (current present status standing position shape situation circumstance) (condition state) (reference or example sample guide gold$3 (error near3 free)) (satisf$6 enough suffice sufficient$3 complet$4 good qualif$4 fulfill$3 pbtain$3 solv$3)	USPAT	AND	ON	2007/03/14 09:36
S31	322	S28 and (reticle or mask)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/14 10:50